

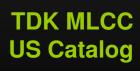
CKD Series Low ESL Feed Through Capacitors

Type:

Issue date:

CKD110JB CKD310JB CKD510JB CKD610JB CKD61BJB

January 2011



Version A11

REMINDERS

Please read before using this product

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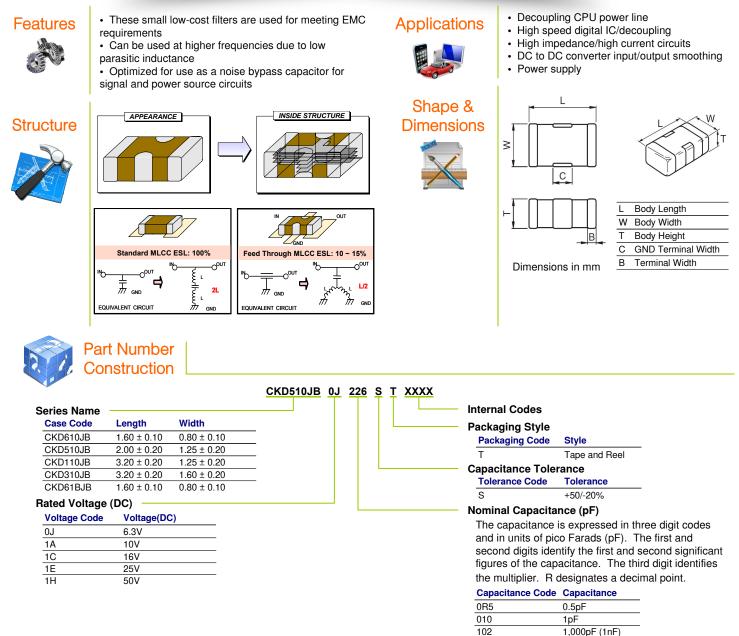
MULTILAYER CERAMIC CHIP CAPACITORS

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CKD Series

Type: CKD610JB (C1608), CKD510JB (C2012), CKD110JB (C3212), CKD310JB (C3216), CKD61BJB (C1608)



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US Catalog // CKD Series – Low ESL Feed Through Capacitors// Version A11

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MULTILAYER CERAMIC CHIP CAPACITORS



CKD610JB [EIA CC0603]

Capacitance Range Chart

Rated voltage	e: 6.3V ((UJ)		_
Capacitance (pF)	Cap Code	Tolerance	0J (6.3V)	
470,000	474	S: +50/-20%		
1,000,000	105			
2,200,000	225			
4,700,000	475			Standard Thickness
10,000,000	106			0.80 ± 0.10 mm



Capacitance Range Table

TDK Part Number (Ordering Code)	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)	Rated Current (Idc) max.	DC Resistance max.
CKD610JB0J105S	6.3V	1,000,000	+50/-20%	0.80 ± 0.10	2000 mA	12 m Ω
CKD610JB0J225S	6.3V	2,200,000	+50/-20%	0.80 ± 0.10	2000 mA	12 m Ω
CKD610JB0J475S	6.3V	4,700,000	+50/-20%	0.80 ± 0.10	2000 mA	12 m Ω

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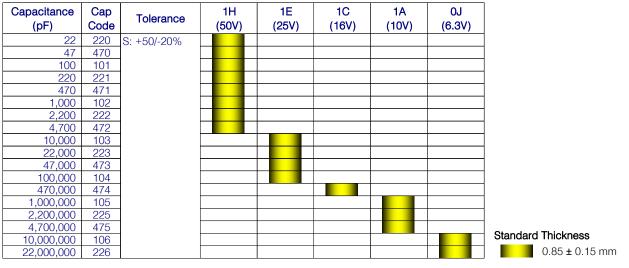
MULTILAYER CERAMIC CHIP CAPACITORS



CKD510JB [EIA CC0805]

Capacitance Range Chart

Rated Voltage: 50V (1H), 25V (1E), 16V (1C), 10V (1A), 6.3V (0J)





Capacitance Range Table

TDK Part Number (Ordering Code)	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)	Rated Current (Idc) max.	DC Resistance max.
CKD510JB1H220S	50V	22	+50/-20%	0.85 ± 0.15	400 mA	500 m Ω
CKD510JB1H470S	50V	47	+50/-20%	0.85 ± 0.15	400 mA	500 m Ω
CKD510JB1H101S	50V	100	+50/-20%	0.85 ± 0.15	400 mA	500 m Ω
CKD510JB1H221S	50V	220	+50/-20%	0.85 ± 0.15	400 mA	500 m Ω
CKD510JB1H471S	50V	470	+50/-20%	0.85 ± 0.15	400 mA	500 m Ω
CKD510JB1H102S	50V	1,000	+50/-20%	0.85 ± 0.15	400 mA	500 m Ω
CKD510JB1H222S	50V	2,200	+50/-20%	0.85 ± 0.15	400 mA	500 m Ω
CKD510JB1H472S	50V	4,700	+50/-20%	0.85 ± 0.15	400 mA	500 m Ω
CKD510JB1E103S	25V	10,000	+50/-20%	0.85 ± 0.15	1000 mA	80 m Ω
CKD510JB1E223S	25V	22,000	+50/-20%	0.85 ± 0.15	1000 mA	80 m Ω
CKD510JB1E473S	25V	47,000	+50/-20%	0.85 ± 0.15	1000 mA	80 m Ω
CKD510JB1E104S	25V	100,000	+50/-20%	0.85 ± 0.15	1000 mA	80 m Ω
CKD510JB1C474S	16V	470,000	+50/-20%	0.85 ± 0.15	2000 mA	30 m Ω
CKD510JB1A105S	10V	1,000,000	+50/-20%	0.85 ± 0.15	2000 mA	12 m Ω
CKD510JB1A225S	10V	2,200,000	+50/-20%	0.85 ± 0.15	2000 mA	12 m Ω
CKD510JB1A475S	10V	4,700,000	+50/-20%	0.85 ± 0.15	3000 mA	12 m Ω
CKD510JB0J106S	6.3V	10,000,000	+50/-20%	0.85 ± 0.15	4000 mA	5 m Ω
CKD510JB0J226S	6.3V	22,000,000	+50/-20%	0.85 ± 0.15	4000 mA	5 m Ω

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MULTILAYER CERAMIC CHIP CAPACITORS



CKD110JB [EIA CC1205]

Capacitance Range Chart

Rated Voltage	e: 25V (1E)		
Capacitance (pF)	Cap Code	Tolerance	1E (25V)	
22	220	S: +50/-20%		
47	470			
100	101			
220	221			
470	471			
1,000	102			
2,200	222			
4,700	472			
10,000	103			
22,000	223			Ohan dan di Thiatan an
47,000	473			Standard Thickness
100,000	104			0.85 ± 0.15 mr



Capacitance Range Table

TDK Part Number (Ordering Code)	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)	Rated Current (Idc) max.	DC Resistance max.
CKD110JB1E220S	25V	22	+50/-20%	0.85 ± 0.15	200 mA	600 m Ω
CKD110JB1E470S	25V	47	+50/-20%	0.85 ± 0.15	200 mA	600 m Ω
CKD110JB1E101S	25V	100	+50/-20%	0.85 ± 0.15	200 mA	600 m Ω
CKD110JB1E221S	25V	220	+50/-20%	0.85 ± 0.15	200 mA	600 m Ω
CKD110JB1E471S	25V	470	+50/-20%	0.85 ± 0.15	200 mA	600 m Ω
CKD110JB1E102S	25V	1,000	+50/-20%	0.85 ± 0.15	200 mA	600 m Ω
CKD110JB1E222S	25V	2,200	+50/-20%	0.85 ± 0.15	200 mA	600 m Ω
CKD110JB1E472S	25V	4,700	+50/-20%	0.85 ± 0.15	200 mA	600 m Ω
CKD110JB1E103S	25V	10,000	+50/-20%	0.85 ± 0.15	500 mA	300 m Ω
CKD110JB1E223S	25V	22,000	+50/-20%	0.85 ± 0.15	500 mA	300 m Ω
CKD110JB1E473S	25V	47,000	+50/-20%	0.85 ± 0.15	500 mA	300 m Ω
CKD110JB1E104S	25V	100,000	+50/-20%	0.85 ± 0.15	500 mA	300 m Ω

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MULTILAYER CERAMIC CHIP CAPACITORS



CKD310JB [EIA CC1206]

Capacitance Range Chart

Rated Voltage: 16V (1C), 6.3V (0J)

Capacitance (pF)	Cap Code	Tolerance	1C (16V)	0J (6.3V)	
100,000	104	S: +50/-20%			
220,000	224				
470,000	474				
1,000,000	105				Standard Thickness
22,000,000	226				1.30 ± 0.30 mm



Capacitance Range Table

TDK Part Number (Ordering Code)	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)	Rated Current (Idc) max.	DC Resistance max.
CKD310JB1C104S	16V	100,000	+50/-20%	1.30 ± 0.30	2000 mA	40 m Ω
CKD310JB1C224S	16V	220,000	+50/-20%	1.30 ± 0.30	2000 mA	40 m Ω
CKD310JB1C474S	16V	470,000	+50/-20%	1.30 ± 0.30	2000 mA	40 m Ω
CKD310JB1C105S	16V	1,000,000	+50/-20%	1.30 ± 0.30	2000 mA	40 m Ω
CKD310JB0J226S	6.3V	22,000,000	+50/-20%	1.30 ± 0.30	4000 mA	12 m Ω

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MULTILAYER CERAMIC CHIP CAPACITORS



CKD61BJB [EIA CC0603]

Capacitance Range Chart

Rated Voltage	e: 6.3V ((OJ)		_
Capacitance (pF)	Cap Code	Tolerance	0J (6.3V)	
100,000	104	S: +50/-20%		
470,000	474			
1,000,000	105			
4,700,000	475			Standard Thickness
10,000,000	106			0.60 ± 0.10 mm



Capacitance Range Table

TDK Part Number (Ordering Code)	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)	Rated Current (Idc) max.	DC Resistance max.
CKD61BJB0J474S	6.3V	470,000	+50/-20%	0.60 ± 0.10	2000 mA	30 m Ω
CKD61BJB0J105S	6.3V	1,000,000	+50/-20%	0.60 ± 0.10	2000 mA	30 m Ω
CKD61BJB0J475S	6.3V	4,700,000	+50/-20%	0.60 ± 0.10	2000 mA	12 m Ω

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CKD Series – Feed Through Capacitors

No.	ltem	Performance	Test or Inspection Method
1	External Appearance	No defects which may affect performance.	Inspect with magnifying glass (3 $ imes$).
2	Insulation Resistance	10,000M Ω or 500M $\Omega \cdot \mu$ F min., whichever smaller (As for the capacitors of rated voltage 16, 10, 6.3V DC, 100M $\Omega \cdot \mu$ F min.).	Apply rated voltage for 60s.
3	Direct Current Resistance R _{dc (1-2)}	R_{dc} is between 5M Ω - 600 M Ω depending on item. See the Capacitance Range Chart section to obtain item specific parameters.	Measuring current should be 100mA max.
4	Voltage Proof	Withstand test voltage without insulation breakdown or other damage.	2.5 x rated voltage (DC) shall be applied for 1 to 5s. Charge / discharge current shall not exceed 50mA.
5	Capacitance	Within the specified tolerance.	Measuring FrequencyMeasuring Voltage1kHz±10%0.5 - 5 Vrms1.0±0.2Vrms1.0±0.2Vrms
6	Dissipation Factor (D.F.)	10% maximum	See No.5 in this table for measuring condition.
7	Bending	No mechanical damage.	Reflow solder the capacitor on P.C. board (shown in Appendix 2, Appendix 4 or Appendix 6) and bend 1mm. 50 F R230 T Unit: mm
8	Solderability	New solder to cover over 75% of termination.	Completely soak both terminations in solder at $235\pm5^{\circ}$ C for 2 ± 0.5 s.
		25% may have pin holes or rough spots but not concentrated in one spot. Ceramic surface of "A sections" shall not be exposed due to melting or shifting of termination material.	Solder: H63A (JIS Z 3282) Flux: Isopropyl alcohol (JIS K 8839) Rosin (JIS K 5902) 25% solid solution.

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MULTILAYER CERAMIC CHIP CAPACITORS



CKD Series – Feed Through Capacitors

No.	Item	Performance	Test o	r Inspection Method			
9	Resistance to so	older heat No mechanical damage.		Completely soak both terminations in solder at $260\pm5^{\circ}$ C for 5 ± 1 s. Preheating condition			
	appearance	No mechanical damage.					
	Capacitance	Change from the value before test		np.: 150±10ºC e: 1 to 2min.			
		± 7.5%		opropyl alcohol (JIS K 8839 osin (JIS K 5902) 25% solic			
	D.F. (Class 2)	Meet the initial spec.	_	H63A (JIS Z 3282)			
	Insulation Resistance	Meet the initial spec.		Leave the capacitor in ambient conditions for 24± before measurement.			
	Voltage Proof	No insulation breakdown or other damage.					
	Resistance for DC (R _{dc})	1.0 Ω max.					
10	Temperature cycle			Reflow solder the capacitor on P.C. board (shown in Appendix 1 or Appendix 3) before testing.			
	External appearance	No mechanical damage.	Expose	Expose the capacitor in the conditions step1 through step 4 and repeat 5 times consecutively.			
	Capacitance	Change from the value before test	Leave the capacitor in ambient conditions for 24±2h before measurement.				
		± 7.5%			Time (main)		
	D.F. (Class 2)	Meet the initial spec.	- <u>Step</u> 1	Temperature (°C)Min. operating temp. ±3	Time (min.) 30 ± 3		
	Insulation	Meet the initial spec.	2	20 ± 2	2-5		
	Resistance	·	3	Max. operating temp. \pm 2	30 ± 2		
	Resistance for DC (R _{dc})	1.0 Ω max.	4	20 ± 2	2 - 5		
11	Moisture Resista	ance (Steady State)		Reflow solder the capacitors on P.C. board (shown			
	External appearance	No mechanical damage.	Appendix 1 or Appendix 3) before testing. Leave at temperature $40\pm2^{\circ}$ C, 90 to 95%RH for 500				
	Capacitance	Change from the value before test	Leave the	 +24,0h. Leave the capacitor in ambient conditions for 24±2h 			
		± 12.5%	before measurement.				
	D.F. (Class 2)	200% of initial spec. max.					
	Insulation Resistance	1,000M Ω or 50M $\Omega \cdot \mu$ F min, whichever smaller. (As for the capacitors of rated voltage 16, 10, 6.3V DC, 10M $\Omega \cdot \mu$ F min.)		-			
	Resistance for DC (R _{dc})	1.0 Ω max.					

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MULTILAYER CERAMIC CHIP CAPACITORS



CKD Series – Feed Through Capacitors

No.	ltem	Performance	Test or Inspection Method		
12	Life		Reflow solder the capacitor on P.C. board (shown in Appendix 1, Appendix 3 or Appendix 5) before testing.		
	External appearance	No mechanical damage.	Voltage shall be applied at maximum operating — temperature $\pm 2^{\circ}$ C for 1,000 +48, 0h.		
	Capacitance	Change from the value before test	Applied voltage is 1xRV; however some items may be tested at higher voltage (1.2x, 1.5x or 2xRV).		
		± 15%	Charge/discharge current shall not exceed 50mA. Leave the capacitor in ambient conditions for $24\pm 2h$		
	D.F. (Class 2)	200% of initial spec. max.			
	Insulation Resistance	1,000M Ω or 50M $\Omega \cdot \mu$ F min., whichever smaller. (As for the capacitors of rated voltage 16, 10, 6.3V DC, 10M $\Omega \cdot \mu$ F min.)	 before measurement. Voltage conditioning: Voltage treats the capacitor under testing temperature and voltage for 1 hour. 		
	Resistance1.0 $Ω$ max.for DC (Rdc)		Leave the capacitor in ambient conditions for $24\pm 2h$ before measurement.		
			Use this measurement for initial value.		

*As for the initial measurement of capacitors on number 9, 10 and 11, leave capacitors at 150–10, 0°C for 1 hour and measure the value after leaving capacitors for 24±2h in ambient condition.

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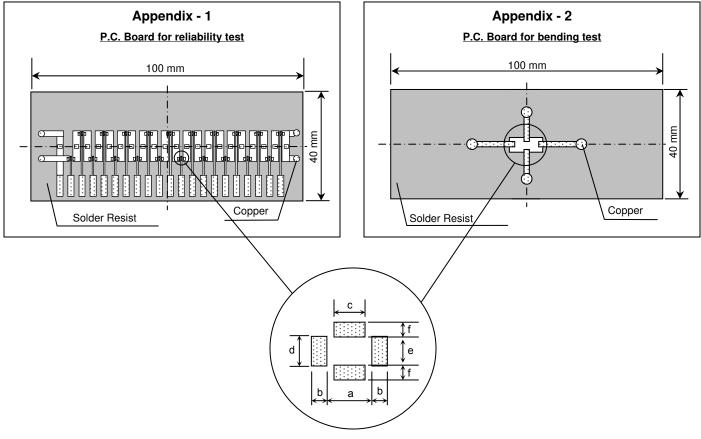
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MULTILAYER CERAMIC CHIP CAPACITORS



General Specifications

CKD Series – Feed Through Capacitors



Appendix – 1 & 2

	Case Code		Dimensions (mm)					
Series	JIS	EIA	а	b	с	d	е	f
CKD710JB	C1005	CC0402	0.7	0.3	0.19	0.6	0.25	0.25

Material: Glass Epoxy (As per JIS C6484 GE4)

P.C. Board thickness: 1.6mm



Copper (thickness 0.035mm)

Solder resist

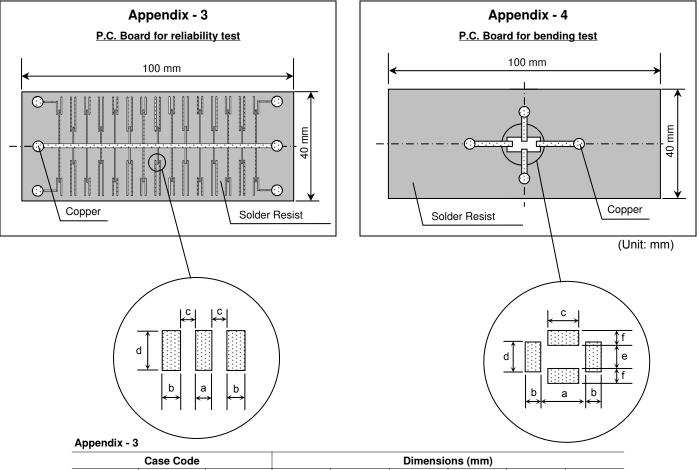
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MULTILAYER CERAMIC CHIP CAPACITORS



General Specifications

CKD Series – Feed Through Capacitors



	Case Code			Dimensio	ons (mm)			
Series	JIS	EIA	а	b	с	d	е	f
CKD610JB	C1608	CC0603	1.0	0.6	0.4	0.6	0.4	0.4

Appendix - 4

	Case Code		Dimensions (mm)				
Series	Series JIS		а	b	с	d	
CKD610JB	C1608	CC0603	0.4	0.5	0.4	2.0	

Material: Glass Epoxy (As per JIS C6484 GE4)

P.C. Board thickness: 1.6mm



Copper (thickness 0.035mm)

Solder resist

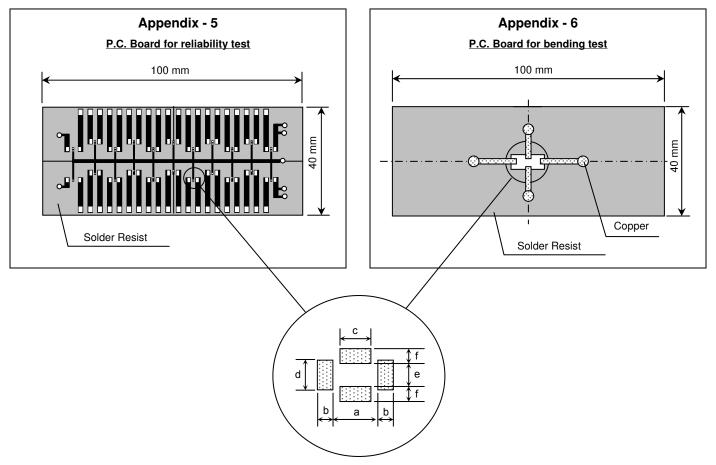
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ER CERAMIC CHIP CAF



General Specifications

CKD Series – Feed Through Capacitors



Appendix – 5 & 6

Case Code			Dimensions (mm)					
Series	JIS	EIA	а	b	с	d	е	f
CKD510JB	C2012	CC0805	1.4	0.6	0.5	0.8	0.6	0.65
CKD110JB	C3212	CC1205	2.5	0.7	1.4	1.0	0.6	0.7
CKD310JB	C3216	CC1206	2.5	1.2	1.4	1.3	0.8	0.9

Material: Glass Epoxy (As per JIS C6484 GE4)

P.C. Board thickness: 1.6mm

Copper (thickness 0.035mm)

Solder resist

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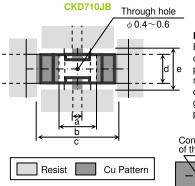
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MULTILAYER CERAMIC CHIP CAPACITORS



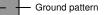
CKD Series – Feed Through Capacitors

Recommended Soldering Land Pattern

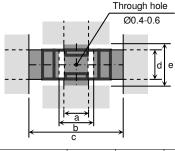


Back side: Back side shall be connected to the ground pattern of the chip mounted side. Please design the back side ground as large as possible.

Connect to the ground pattern of the chip mounted side.

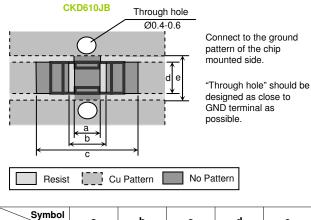


CKD510JB, CKD110JB, CKD310JB



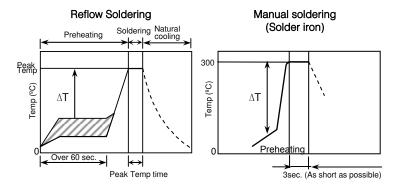
*If through hole is too big, solder paste may come into the hole and make bad connection with the ground pattern.

Symbol а b С d е Series CKD710JB 0.19 0.6 0.75 0.7 1.3 CKD510JB 0.5 1.5 2.6 1.0 2.0 CKD110JB 2.5 1.0 1.4 4.5 2.0 CKD310JB 1.4 2.5 4.5 1.2 2.4



Symbol Series	а	b	с	d	е
CKD610JB	0.4	1.2	2.2	0.7	1.4

Recommended Soldering Profile



Recommended soldering duration

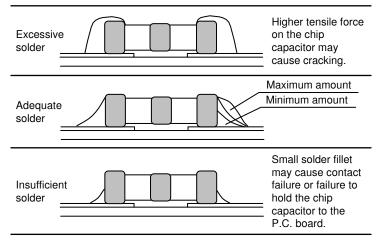
Temp./	Reflow S	Soldering
Dura. Solder	Peak temp (°C)	Duration (sec.)
Sn-Pb Solder	230 max.	20 max.
Lead-Free Solder	260 max.	10 max.

Recommended solder compositions Sn-37Pb (Sn-Pb solder) Sn-3.0Ag-0.5Cu (Lead Free Solder)

Preheating Condition

Soldering Method	Temperature (ºC)
Reflow soldering	∆T ≤ 150
Manual soldering	∆T ≤ 150

Recommended Solder Amount



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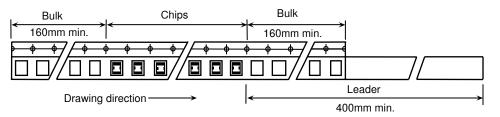
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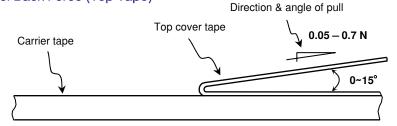


CKD Series – Feed Through Capacitors

• Carrier Tape Configuration



• Peel Back Force (Top Tape)

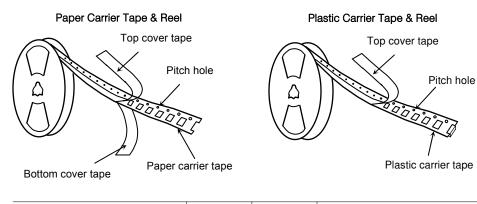


• Carrier tape shall be flexible enough to be wound around a minimum radius of 30mm with components in tape.

 \bullet The missing of components shall be less than 0.1%

Components shall not stick to the cover tape.
The cover tape shall not protrude beyond the edges of the carrier tape not shall cover the sprocket holes.

Chip Quantity Per Reel and Structure of Reel (Paper & Plastic)



Ca	Case Code		Chip	Toning	Chip quar	ntity (pcs.)
Series	JIS	EIA	Thickness (mm)	Taping Material	φ178mm (7") reel	φ330mm (13") reel
CKD710JB	C1005	CC0402	0.30		10,000	50,000
CKD610JB	C1608	CC0603	0.80	Banar		
CKD510JB	C2012	CC0805	0.85	Paper	4,000	10.000
CKD110JB	C3212	CC1205	0.85			10,000
CKD310JB	C3216	CC1206	1.30	Plastic	2,000	

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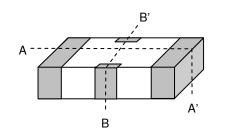
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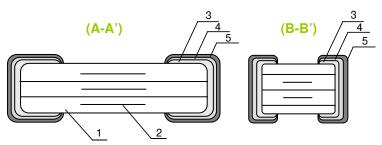
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CKD Series – Feed Through Capacitors

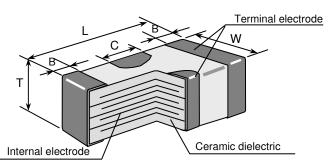
Inside Structure & Material System





No.	NAME	MATERIAL
(1)	Ceramic Dielectric	CaZrO ₃ or BaTiO ₃
(2)	Internal Electrode	Nickel (Ni)
(3)		Copper (Cu)
(4)	Termination	Nickel (Ni)
(5)		Tin (Sn)

Shape & Dimensions



Ca		Dimensions (mm)						
Series	JIS	EIA	L	W	Т	В	С	
CKD710JB	C1005	CC0402	1.00	0.55	0.30	0.17	0.30	
CKD610JB	C1608	CC0603	1.60	0.80	0.80	0.10	0.40	
CKD510JB	C2012	CC0805	2.00	1.25	0.85	0.30	0.40	
CKD110JB	C3212	CC1205	3.20	1.25	0.85	0.40	0.95	
CKD310JB	C3216	CC1206	3.20	1.60	1.30	0.40	0.95	

• All specifications are subject to change without notice. Please read the precautions before using the product.

• Environmental Information

TDK Corporation established internal product environmental assurance standards that include the six hazardous substances banned by the EU RoHS Directive¹ enforced on July 1, 2006 along with additional substances independently banned by TDK and has successfully completed making general purpose electronic components conform to the RoHS Directive².

- Abbreviation for Restriction on Hazardous Substances, which refers to the regulation EU Directive 2002/95/EC on hazardous substances by the European Union (EU) effective from July 1, 2006. The Directive bans the use of six specific hazardous substances in electric and electronic devices and products handled within the EU. The six substances are lead, mercury, cadmium, hexavalent chromium, PBB (polybrominated biphenyls), and PBDE (polybrominated diphenyl ethers).
- This means that, in conformity with the EU Directive 2002/95/EC, lead, cadmium, mercury, hexavalent chromium, and specific bromine-based flame retardants, PBB and PBDE, have not been used, except for exempted applications.
- For REACH (SVHC : 15 substances according to ECHA / October 2008) : All TDK MLCC do not contain these 15 substances.
- For European Directive 2000/53/CE and 2005/673/CE : Cadmium, Hexavalent Chromium, Mercury, Lead are not contained in all TDK MLCC.
- For European Directive 2003/11/CE : Pentabromodiphenyl-ether, Octabromodiphenyl-ether are not contained in all TDK MLCC.